



## **Guidelines for 3D InCites Article Contributors**

3D InCites is an online content source founded in 2009 in an effort to stir up interest in 3D IC integration and 3D packaging technologies. For 3D integration to happen requires open collaboration across the supply chain. Therefore, 3D InCites strives to inform key decision makers about progress in technology development, design, standards, and infrastructure in order to realize commercial production of 2.5D and 3D technologies.

As 3D InCites is intended to be an online community, we encourage contributions in the form of guest blogs original technology features, and previously published white papers. We have created these guidelines to help you get your work published on 3D InCites in a timely fashion.

### **Steps for Publication:**

- Submit a 100-200 word abstract of the topic you'd like to write about. Once approved, a deadline date will be agreed upon. Since 3D InCites is an online publication and frequently updated, deadlines are somewhat flexible. We do ask that you stick to the agreed-upon deadline so that we can schedule workflow accordingly.
- Register and create a full profile with your headshot and bio on 3D InCites at [www.3dincites.com/register](http://www.3dincites.com/register). This is your byline and all posts by you will link to your profile.
- Once your abstract is approved for publication, you will be granted contributed privileges, which gives you limited access to the WordPress back-end of 3D InCites. We will be happy to walk you through the process of publishing on WordPress if needed. You will also be able to upload accompanying figures for your post.
- Guest Blog posts (editorial comment) should be 500-700 words, with no more than 3 figures in .jpg or .png format. Image files must be under 2MB.
- Technology features should be 800-1000 words, 3-5 figures maximum.
- All posts are subject to the approval of 3D InCites editors and once posted will remain in pending mode until approved for publication.
- Once published, 3D InCites editors will share your post via 3D InCites social media platforms. Additionally the post will be included in the next available weekly update that is distributed to over 1200 registered members.



**Criteria for acceptance:**

- Originality is key. We do not require contributors to assign a copyright to 3D InCites, however we do request your feature contributions and guest blog posts be original for 3D InCites. Subsequent publication in other media sources should include the statement that this article “appeared first on 3D InCites” with a link to the post.
- We are also happy to repost and make available for download, white papers in pdf form that have been previously published by industry organizations or presented at conferences. These will be posted in our Resource Library. Contact the organization involved to see if they have any required credit line that must be used.
- Advance the state of knowledge of 3D packaging, 3D IC, and monolithic 3D approaches to 3D Integration, 3D system integration, 2.5D interposer technology, or 3D MEMS.
- Be free of commercialism and marketing hype.
- Be well written with solid technical content that will be understandable by the majority of our readers.
- To ensure the highest quality in our publication, abstracts may be reviewed not only by 3D InCites editorial director, but submitted to our technical advisory board for further review before acceptance.

**Submit your abstract to Françoise von Trapp, [francoise@3DInCites.com](mailto:francoise@3DInCites.com)**